



# Product Change Notification

**Change Notification #:** 915594-00  
**Change Title:** Select Intel® Ethernet Network Adapter OCP3.0 E810-XXVDA4  
**Change Detail:** Replacing E810-DA4 4X10/25G OCP Ethernet Bracket With Insulated Faceplate  
**Date of Publication:** March 23, 2026

## Key Characteristics of the Change:

Product Material

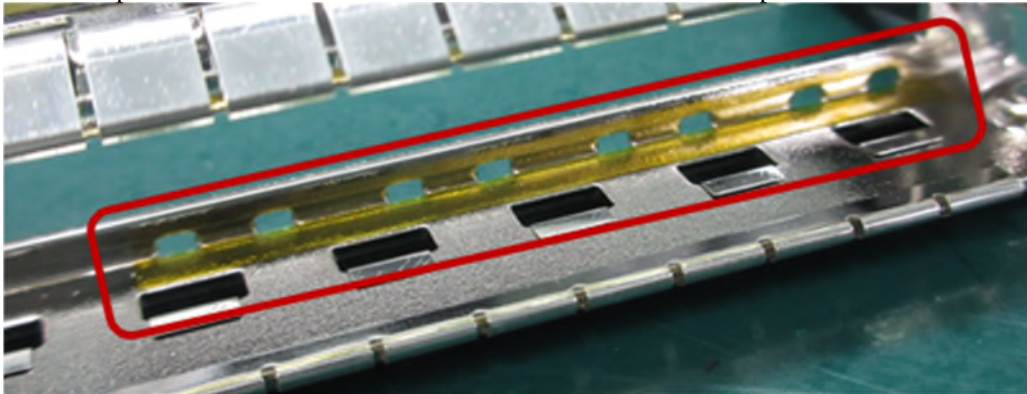
## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material</b>	May 29, 2026
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## Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

A 0.05mm Kapton insulating film (rated to 260°C) is applied to the inner surface of the J96050-00X/K35854-00X bracket to prevent electrical contact between the LED and bracket faceplate.



As a result of these changes, the Printed Board Assembly (PBA) and Top Assembly (TA) numbers will roll as noted in the affected products table within this PCN notice. If the PBA/TA numbers are printed on any product or box labels, those will show the PBA/TA dash roll as well.

## Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Customers are expected to receive a mixed inventory consisting of insulated brackets stamped J96050-003 and insulated brackets with the updated J96050-004 stamping.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

## Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Intel® Ethernet Network Adapter OCP3.0 E810-XXVDA4	E810XXVDA4OCP3G	983100	M33395-005	K80838-008	M33395-006	K80838-009
Intel® Ethernet Network Adapter OCP3.0 E810-XXVDA4	E810XXVDA4OCPV3	983099	M33397-005	M33399-005	M33397-006	M33399-006

## PCN Revision History:

**Date of Revision:**

March 23, 2026

**Revision Number:**

00

**Reason:**

Originally Published PCN



# Product Change Notification

## 915594-00

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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

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